

Patent Abstracts of Japan

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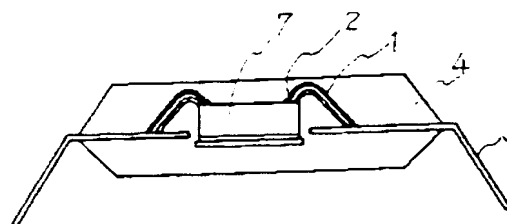
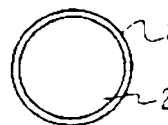
APPLICATION DATE : 14-12-89
APPLICATION NUMBER : 01325121

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TITLE : BONDING WIRE FOR
SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To prevent a short circuit and a disconnection even when a deformed loop is touched by a method wherein the surface of a conductive wire is coated with an insulating material which is melted or evaporated at a temperature of a bonding temperature or higher.

CONSTITUTION: The surface of a metal wire is coated with a material which is provided with an insulating property and which is melted or evaporated at a bonding temperature or higher (350°C or higher). For example, a coating film 1 with which the surface of a conductive wire 2 is coated uniformly has a film thickness of 1μm; the conductive wire 2 of Al is formed by being immersed in a silicone oil and by being dried. Thereby, even when the wire is loosened, no short circuit nor disconnection is caused.

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